KAMAYA OHM

No.: RAAW-K-HTS-0001 /3
Date: 2020. 5. 29

Data sheet

Title: FIXED CHIP RESISTOR NETWORKS; RECTANGULAR

TYPE

Style: RAAW06 2D, RAAW06 4D

AEC-Q200 qualified

RoHS COMPLIANCE ITEM Halogen and Antimony Free

Note: •Stock conditions

Temperature: $+5^{\circ}\text{C} \sim +35^{\circ}\text{C}$ Relative humidity: $25\% \sim 75\%$

The period of guarantee: Within 2 year from shipment by the company.

Solderability shall be satisfied.

- Product specification contained in this data sheet are subject to change at any time without notice
- •If you have any questions or a Purchasing Specification for any quality Agreement is necessary, please contact our sales staff.



Hokkaido Research Center Approval by: T. Sannomiya Drawing by: M. Shibuya AMAYA OHM No: RAAW-K-HTS-0001 /3

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Title: FIXED CHIP RESISTOR NETWORKS; RECTANGULAR TYPE
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1. Scope

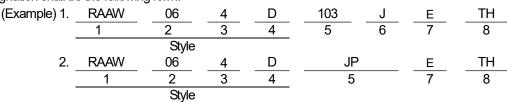
1.1 This data sheet covers the detail requirements for fixed chip resistor networks; rectangular type, style of RAAW06 2D, RAAW06 4D.

1.2 Applicable documents

JIS C 5201-1: 2011, JIS C 5201-9: 2006, JIS C 5201-9-1: 2006 IEC60115-1: 2008, IEC60115-9: 2004, IEC60115-9-1: 2004

2. Classification

Type designation shall be the following form.



Style

- 1 Fixed chip resistor networks; rectangular type
- 2 Size
- 3 Number of elements
- 4 Circuits
- 5 Rated resistance

ĺ	103	E24 Series, 3 digit,	Ex. 103> 10kΩ,
	JP	Chip jumper	

6 Tolerance on rated resistance

F	±1%
J	±5%

7 Terminal style

al Style						
E	Convoy Turo	Flat Type Low profile (Face down)				
G	Convex Type	Flat Type Low profile (Face up)				

8 Packaging form

В	Bulk (loose package)
TH	Paper taping

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3. Rating

3.1 The ratings shall be in accordance with Table-1.

Table-1

Style	Terminations style	Rated element dissipation (W)	Temperature coefficient of resistance (10 ⁻⁶ / °C)	Rated resistance range(Ω)	Preferred number series for resistors	Tolerance on rated resistance
		0.031	±200	100~100k	E24	F(±1%)
RAAW06 2D	E, G		±350	10~27		1/+50/\
			±200	30~1M		J(±5%)
		0.031	±200	100~100k		F(±1%)
RAAW064D	E, G		±350	10~27	E24	1/+50/-)
			±200	30~1M		J(±5%)

Style	Limiting element voltage(V)	Insulation voltage(V)	Number of elements	Circuit networks	Category temperature range(°C)
RAAW06 2D	12.5	50	2	D	<i>–</i> 55∼+155
RAAW064D	12.5	30	4	(Independence type)	-55~+155

Note. Rated current of chip jumper: 1(A)

Note. Resistance value of chip jumper: $50m\Omega$ max.

3.2 Climatic category

55/155/56 Lower category temperature -55 °C
Upper category temperature +155 °C
Duration of the damp heat, steady state test 56days

3.3 Stability class

5% Limits for change of resistance:

-for long–term tests \pm (5%+0.1Ω) Chip jumper: 50 mΩ max. -for short–term tests \pm (1%+0.05Ω) Chip jumper: 50 mΩ max.

3.4 Derating

The derated values of dissipation (or current rating in case of chip jumper) at temperature in excess of 70 °C shall be as indicated by the following curve.

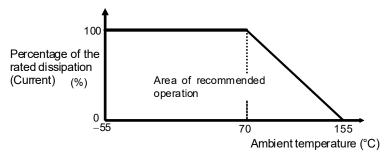


Figure-1Derating curve



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3.5 Rated voltage

d. c. or a. c. r. m. s. voltage calculated from the square root of the product of the rated resistance and the rated dissipation.

Limiting element voltage can only be applied to resistors when the resistance value is equal to or higher than the critical resistance value.

At high value of resistance, the rated voltage may not be applicable.

4. Packaging form

The standard packaging form shall be in accordance with Table-2.

Table-2

Symbol	F	ackaging form	Standard packaging quantity / units
В	Bulk (loose pacl	1,000 pcs.	
TH	Paper taping 8mm width, 2mm pitches		10,000 pcs.

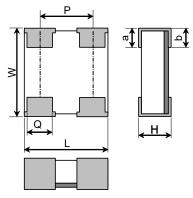
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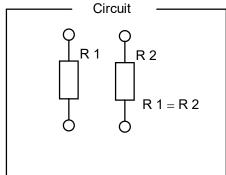
5. Dimensions

The resistor shall be of the design and physical dimensions in accordance with below.

5.1 Terminations style:E.[Flat Type Low profile (Face down)]







5.1.2 RAAW06 4D

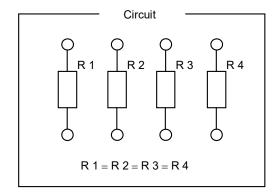


Figure-2

Figure-3

Table–3 Unit: mm

Style	Terminations style	L	W	Н	*Q	а	b	*P
RAAW06 2D	E	0.8±0.05	0.6±0.05	0.23±0.10	0.2±0.1	0.2±0.1	0.2±0.1	0.5
RAAW06 4D	Е	1.4±0.05	0.6±0.05	0.23±0.10	0.2±0.1	0.2±0.1	0.2±0.1	0.4

*Reference

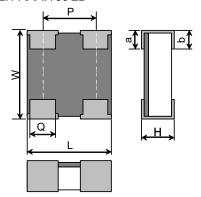
5.1.3 Net weight (Reference)

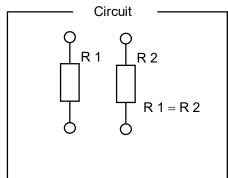
Style	Terminations style	Net weight(mg)
RAAW06 2D	E	0.38
RAAW06 4D	Е	0.65

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5.2 Terminations style:G.[Flat Type Low profile (Face up)]

5.2.1 RAAW06 2D





5.2.2 RAAW06 4D

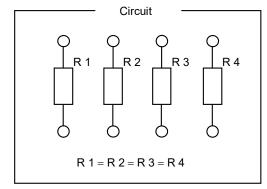


Figure-4

Figure-5

Table-4						Unit: mm	<u> </u>	
Style	Terminations style	L	W	Н	*Q	а	b	*P
RAAW06 2D	G	0.8±0.05	0.6±0.05	0.23±0.10	0.2±0.1	0.2±0.1	0.2±0.1	0.5
RAAW064D	G	1 4+0 05	0.6+0.05	0.23+0.10	0.2+0.1	0.2+0.1	0.2+0.1	0.4

*Reference

5.2.3 Net weight (Reference)

	/	
Style	Terminations style	Net weight(mg)
RAAW06 2D	G	0.38
RAAW06 4D	G	0.65

6. Marking

The Rated resistance of RAAW06 2D, 4D should not be marked.



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7. Performance

7.1 The standard condition for tests shall be in accordance with Sub-clause 4. 2, JIS C 5201–1: 2011.

7.2 The performance shall be satisfied in Table-5.

Table-5(1)

No.	Test items	Condition of test (US C 5201, 1)	Performance requirements
		Condition of test (JIS C 5201–1)	·
1	Visual examination	Sub-clause 4. 4. 1	As in 4. 4. 1
		Checked by visual examination.	The marking shall be legible, as
	5:		checked by visual examination.
2	Dimension	Sub-clause 4. 4. 2	As specified in sub clause5 of this
	Building		specification.
	Resistance	Sub-clause 4. 5	As in 4. 5. 2
			The resistance value shall
			correspond with the rated resistance taking into account the specified
			tolerance.
3	Voltage proof	Sub-clause 4. 7	Chip jumper: 50 mΩ max. No breakdown or flash over
٥	voltage proof	Method: 4. 6. 1. 4	I NO DIEGRACOWITOI IIGSITOVEI
		Test voltage: Alternating voltage with a peak	
		value of 1.42 times the insulation voltage.	
		Duration: 60 s ± 5 s	
		Insulation resistance	R≥1GΩ
		Test voltage: Insulation voltage	112132
		Duration: 1 min.	
4	Solderability	Sub-clause 4. 17	As in 4. 17. 4. 5
	,	Without ageing	The terminations shall be covered
		Flux: The resistors shall be immersed in a	with a smooth and bright solder
		non-activated soldering flux for 2s.	coating.
		Bath temperature: 235 °C ± 5 °C	
		Immersion time: 2 s ± 0.5 s	
5	Mounting	Sub-clause 4. 31	
		Substrate material: Epoxide woven glass	
		Sub-clause 4. 13	
	Overload	The applied voltage shall be 2.5 times the rated	
	(in the mounted state)	voltage or twice the limiting element voltage,	
		whichever is the less severe.	
		Duration: 2 s	No visible demage
		Visual examination	No visible damage
		Resistance	$\Delta R \le \pm (1\% + 0.05\Omega)$
	Solvent resistance of the	0.1	Chip jumper: 50 mΩ max.
	marking	Sub-clause 4. 30	Legible marking
	Thanking	Solvent: 2–propanol	
		Solvent temperature: 23°C±5°C	
		Method 1	
		Rubbing material: cotton wool	
		Without recovery	



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Table-5(2)

T19	1able-5(2)	D-4
		Performance requirements
Mounting		
Daywal atmospeths of the cond	,	
face plating		
	Resistance	$\Delta R \leq \pm (1\% + 0.05\Omega)$
		Chip jumper: 50 m Ω max.
Final measurements	Sub-clause 4. 33. 6	No visible damage
	Visual examination	
Resistance to soldering heat	Sub-clause 4. 18	
	Solder temperature: 260°C±5°C	
	Immersion time: 10s±0.5s	
	Visual examination	As in 4. 18. 3. 4
		No sign of damage such as cracks.
	Resistance	$\Delta R \leq \pm (1\% + 0.05\Omega)$
		Chip jumper: $50 \mathrm{m}\dot{\Omega}$ max.
Component solvent	Sub-clause 4.29	
resistance	Solvent: 2-propanol	
		No visible damage
		$\Delta R \leq \pm (1\% + 0.05\Omega)$
	T tooloan to	Chip jumper: $50 \text{ m}\Omega$ max.
Mounting	Sub-clause 4, 31	
S .		
Adhesion		
		No visible damage
Rapid change temperature		3
	·	
		No visible damage
		$\Delta R \leq \pm (1\% + 0.05\Omega)$
	1 tooloidi 100	Chip jumper: $50 \text{ m}\Omega$ max.
	Component solvent resistance Mounting Adhesion	Mounting Sub-clause 4. 31 Substrate material: Epoxide woven glass Sub-clause 4. 33 Bent value: 3 mm Resistance Final measurements Sub-clause 4. 33. 6 Visual examination Resistance to soldering heat Sub-clause 4. 18 Solder temperature: 260°C±5°C Immersion time: 10s±0.5s Visual examination Resistance Component solvent resistance Sub-clause 4.29 Solvent: 2-propanol Solvent temperature: 23°C±5°C Method 2 Recovery: 48 h Visual examination Resistance Mounting Sub-clause 4. 31 Substrate material: Epoxide woven glass Sub-clause 4. 32 Force: 3 N Duration: 10s±1s Visual examination



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Table-5(3)

No	Test items	Condition of test (JIS C 5201 - 1)	Performance requirements		
9	Climatic sequence Sub-clause 4. 23				
	-Dry heat	Sub-clause 4. 23. 2			
		Test temperature: +155 °C			
		Duration: 16 h			
	–Damp heat, cycle	Sub-clause 4. 23. 3			
	(12+12hour cycle)	Test method: 2			
	First cycle	Test temperature: 55 °C			
		[Severity(2)]			
	-Cold	Sub-clause 4. 23. 4			
		Test temperature–55 °C			
		Duration: 2h			
	-Damp heat, cycle	Sub-clause 4. 23. 6			
	(12+12hourcycle)	Test method: 2			
	Remaining cycle	Test temperature: 55 °C			
		[Severity (2)]			
		Number of cycles: 5 cycles			
	–D.C. load	Sub-clause 4. 23. 7			
		The applied voltage shall be the rated voltage or			
		the limiting element voltage whichever is the			
		smaller.			
		Duration: 1 min.	No visible damage		
		Visual examination	$\Delta R \le \pm (5\% + 0.1\Omega)$		
		Resistance	Chip jumper: $50 \text{ m}\Omega$ max.		
10	Mounting	Sub-clause 4. 31	Chip jumper. 30 msz max.		
10	iviouriting	Substrate material: Epoxide woven glass			
	Endurance at 70 °C	Sub-clause 4. 25. 1			
	Endarance at 70°C	Ambient temperature: 70°C±2°C			
		Duration: 1000 h			
		The voltage shall be applied in cycles of 1. 5 h			
		on and 0.5 h off.			
		The applied voltage shall be the rated voltage or			
		the limiting element voltage whichever is the			
		smaller.			
		Examination at 48 h , 500 h and			
		1000 h:			
		Visual examination	No visible damage		
		Resistance	$\Delta R \le \pm (5\% + 0.1\Omega)$		
			Chip jumper: 50 m Ω max.		



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Table-5(4)

No	Test items	Condition of test (JIS C 5201 - 1)	Performance requirements	
11	Mounting		renormance requirements	
111	Modriting	Sub-clause 4. 31 Substrate material: Epoxide woven glass		
	Variation of resistance with	Sub-clause 4. 8	As in Table–1	
	temperature	Sub-clause 4. 6 -55 °C / +20 °C	AS IT Table—T	
	temperature	-55 C / +20 C +20 °C / +155°C		
12	Mounting			
12	Mounting	Sub-clause 4. 31		
	Damp heat, steady state	Substrate material: Epoxide woven glass		
		Sub-clause 4. 24		
		Ambient temperature: 40°C±2°C		
		Relative humidity: 93 + 3 %		
		a) 1st group: without voltage applied.		
		b) 2nd group: The d. c. voltage shall be applied		
		continuously. The voltage shall be accordance with		
		Sub-clause 4. 24. 2 .1 b). without polarizing		
		voltage [4. 24. 2. 1, c)] Visual examination	No visible damage	
		Visual examination	Legible marking	
		Resistance	$\Delta R \le \pm (5\% + 0.1\Omega)$	
			Chip jumper: 50 m Ω max.	
13	Dimensions (detail)	Sub-clause 4. 4. 3	As in Sub-clause 5 of this specification	
	Mounting	Sub-clause 4. 31	'	
		Substrate material: Epoxide woven glass		
	Endurance at upper category temperature	Sub-clause 4. 25. 3		
		Ambient temperature:155°C±2°C		
		Duration: 1000 h		
		Examination at 48 h, 500 h and 1000 h:		
		Visual examination	No visible damage	
		Resistance	$\Delta R \le \pm (5\% + 0.1\Omega)$	
			Chip jumper: $50 \mathrm{m}\Omega$ max.	
14	Humid Sulfur vapor test	ASTM B809		
	(FOS)	Reagent: Sulfur (Saturated vapor)		
		Test temp.: 60°C		
		Relative humidity: 95%RH		
		Test period: 1000 h		
		Resistance	$\Delta R \le \pm (1\% + 0.05\Omega)$	
			Chip jumper: $50 \text{m}\Omega$ max.	

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8. Taping

- 8.1 Applicable documents JIS C 0806-3: 2014, EIAJ ET-7200C: 2010
- 8.2 Taping dimensions
- 8.2.1 Paper taping (8mm width, 2mm pitches)

Taping dimensions shall be in accordance with Figure-6 and Table-6.

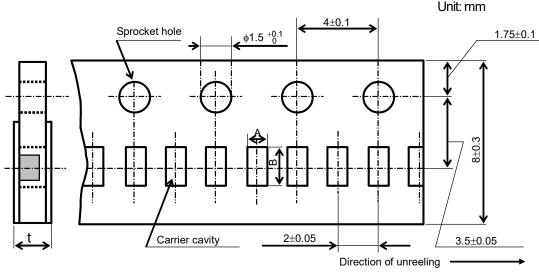
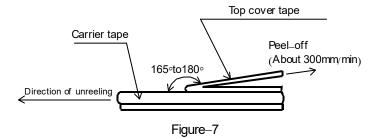


Figure-6

Table-6			Unit: mm
Style	Α	В	t
RAAW06 2D	0.7±0.1	0.9±0.1	0.6 max.
RAAW064D	0.7±0.1	1.5±0.1	

- 1). The cover tapes shall not cover the sprocket holes.
- 2). Tapes in adjacent layers shall not stick together in the packing.
- 3). Components shall not stick to the carrier tape or to the cover tape.
- 4). Pitch tolerance over any 10 pitches ±0.2mm.
- 5). The peel strength of the top cover tape shall be with in 0.1N to 0.5N on the test method as shown in the following Figure–7.
- 6). When the tape is bent with the minimum radius for 25 mm, the tape shall not be damaged and the components shall maintain their position and orientation in the tape.
- 7). In no case shall there be two or more consecutive components missing.

 The maximum number of missing components shall be one or 0.1%, whichever is greater.
- 8). The resistors shall be faced to upward at the over coating side in the carrier cavity.



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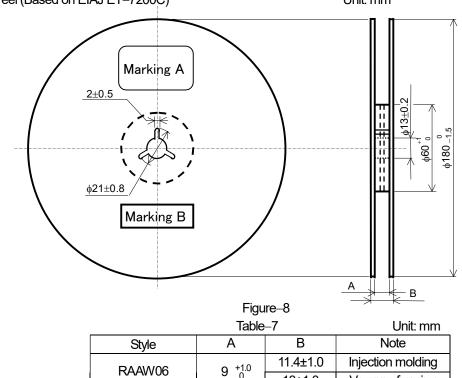
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8.3 Reel dimension

Reel dimensions shall be in accordance with the following Figure–8 and Table–7. Plastic reel (Based on EIAJ ET–7200C)

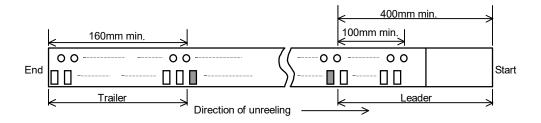
Unit: mm



Note: Marking label shall be marked on a place of Marking A or two place of marking A and B.

8.4 Leader and trailer tape.

(Example)



13±1.0

Vacuum forming

Figure-9

9. Marking on package

The label of a minimum package shall be legibly marked with follows.

- 9.1 Marking A
 - (1) Classification (Style, Rated resistance, Tolerance on rated resistance, Terminal style, Packaging form)
 - (2) Quantity (3) Lot number (4) Manufacturer's name or trade mark (5) Others
- 9.2 Marking B (KAMAYA Control label)

单击下面可查看定价,库存,交付和生命周期等信息

>>Kamaya(釜屋电机)